68. A chip package comprising:

packaging material having a first side and a second side,

a lead extending from the first side of the packaging material, and

a first clip portion extending from a second side of the packaging material.

69. The chip package of claim 68, further comprising a second clip portion extending from a third side of the packaging material.

70. The chip package of claim 69, further comprising a flexible insert residing between the lead and the first side of the packaging material, wherein the flexible insert supplies spring force when the lead is compressed.

71. The chip package of claim 70, wherein the flexible insert is cylindrical.

72. The chip package of claim 71, wherein the flexible insert is a compliant material.

73. The chip package of claim 72, wherein the compliant material is an elastomer.

74. The chip package of claim 70, wherein the lead is substantially C-shaped.

75. The chip package of claim 74, wherein the lead is compressible.

76. The chip package of claim 70, wherein the lead is compressible.

77. The chip package of claim 68, further comprising a support pin extending from the packaging material.

78. The chip package of claim 69, wherein the first and second clip portions are integral with the packaging material.

79. The chip package of claim 68, wherein the lead is a flexible metallic material.

80. The chip package of claim 78, wherein the metallic material comprises beryllium-copper.

81. The chip package of claim 68, wherein the packaging material is comprised of a flexible material.

82. The chip package of claim 81, wherein the flexible material supplies spring force when the lead is compressed.

83. The chip package of claim 68, wherein the packaging material comprises silicone rubber.

84. The chip package of claim 68, further comprising a cam follower extending from the packaging material.

85. The chip package of claim 68, further comprising an integrated circuit disposed in the packaging material.

86. The chip package of claim 69, wherein the first and second clip portions are flexible.

87. The chip package of claim 68, wherein the packaging material has a bottom-facing housing that extends laterally from the packaging material, the bottom-facing housing having a pocket formed therein.

88. The chip package of claim 87, wherein an end of the lead is disposed within

the pocket when the lead is compressed.

89. A package, comprising:

an integrated circuit enclosed with the package,

substantially C-shaped leads at a first end of the package,

a guide member on a side of the package, wherein the guide member has a ramp, and

mechanical support pins at a second end of the package opposite the first end,

wherein the package resides substantially horizontally with respect to a circuit board when the package is inserted in a base assembly coupled to the circuit board.

90. The package of claim 89, wherein the integrated circuit is a dynamic random access memory device.

Respectfully Submitted,

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